Single 2-Input OR Gate

The NL17SZ32 is a single 2-input OR Gate in two tiny footprint packages. The device performs much as LCX multi-gate products in speed and drive. They should be used wherever the need for higher speed and drive are needed.

Features

- Tiny SOT-353 and SOT-553 Packages
- 2.4 ns T_{PD} at 5.0 V (typ)
- Source/Sink 24 mA at 3.0 V
- Over-Voltage Tolerant Inputs
- Pin For Pin with NC7SZ32P5X, TC7SZ32FU and TC7SZ32AFE
- Chip Complexity: FETs = 20
- Designed for 1.65 V to 5.5 V V_{CC} Operation
- Pb-Free Packages are Available

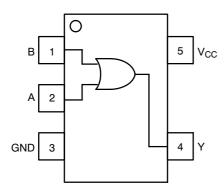


Figure 1. Pinout (Top View)

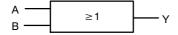


Figure 2. Logic Symbol



ON Semiconductor®

http://onsemi.com



SOT-353/SC70-5/SC-88A **DF SUFFIX CASE 419A**



MARKING





SOT-553 **XV5 SUFFIX CASE 463B**



= Specific Device Code L4

М = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

PIN ASSIGNMENT

Pin	Function		
1	В		
2	Α		
3	GND		
4	Υ		
5	V _{CC}		

FUNCTION TABLE

Inp	out	Output Y = A + B
Α	В	Y
L	L	L
L	Н	Н
Н	L	Н
Н	Н	Н

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol	Parame	ter	Value	Unit
V _{CC}	DC Supply Voltage	-0.5 to +7.0	V	
V _{IN}	DC Input Voltage		-0.5 to +7.0	V
V _{OUT}	DC Output Voltage		-0.5 to V_{CC} $+0.5$	V
I _{IK}	DC Input Diode Current		-50	mA
I _{OK}	DC Output Diode Current		-50	mA
I _{OUT}	DC Output Sink Current		±50	mA
I _{CC}	DC Supply Current per Supply Pin	± 100	mA	
T _{STG}	Storage Temperature Range	-65 to +150	°C	
T _L	Lead Temperature, 1 mm from Case for 10 S	Seconds	260	°C
TJ	Junction Temperature Under Bias		+ 150	°C
$\theta_{\sf JA}$	Thermal Resistance	SOT-353 (Note 1) SOT-553	350 496	°C/W
P _D	Power Dissipation in Still Air at 85°C SOT-353 SOT-553		186 135	mW
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
ESD	ESD Classification	Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	Class Z Class A N/A	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.

2. Tested to EIA/JESD22-A114-A, rated to EIA/JESD22-A114-B.

- 3. Tested to EIA/JESD22-A115-A, rated to EIA/JESD22-A115-A.
- 4. Tested to JESD22-C101-A.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	DC Supply Voltage	1.65	5.5	٧
V _{IN}	DC Input Voltage	0	5.5	٧
V _{OUT}	DC Output Voltage	0	V _{CC} + 0.5	٧
T _A	Operating Temperature Range	-40	+85	°C
t _r , t _f	Input Rise and Fall Time $ \begin{array}{c} V_{CC} = 3.0 \ V \pm 0. \\ V_{CC} = 5.0 \ V \pm 0. \end{array} $	3 V 0 5 V 0	100 20	ns/V

DC ELECTRICAL CHARACTERISTICS

			V _{CC}	T _A = 25°C		С	-40°C ≤	T _A ≤ 85°C	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
V _{IH}	High-Level Input Voltage		1.65 to 1.95 2.3 to 5.5	0.75 V _{CC} 0.7 V _{CC}			0.75 V _{CC} 0.7 V _{CC}		V
V _{IL}	Low-Level Input Voltage		1.65 to 1.95 2.3 to 5.5			0.25 V _{CC} 0.3 V _{CC}		0.25 V _{CC} 0.3 V _{CC}	V
V _{OH}	High-Level Output Voltage	I _{OH} = 100 μA	1.65 to 5.5	V _{CC} - 0.1	V _{CC}		V _{CC} - 0.1		V
	$V_{IN} = V_{IL} \text{ or } V_{IH}$	$I_{OH} = -3 \text{ mA}$	1.65	1.29	1.52		1.29		
		$I_{OH} = -8 \text{ mA}$	2.3	1.9	2.1		1.9		
		$I_{OH} = -12 \text{ mA}$	2.7	2.2	2.4		2.2		
		$I_{OH} = -16 \text{ mA}$	3.0	2.4	2.7		2.4		
		$I_{OH} = -24 \text{ mA}$	3.0	2.3	2.5		2.3		
		$I_{OH} = -32 \text{ mA}$	4.5	3.8	4.0		3.8		
V _{OL}	Low-Level Output Voltage	I _{OL} = 100 μA	1.65 to 5.5			0.1		0.1	V
	$V_{IN} = V_{IH} \text{ or } V_{OH}$	$I_{OL} = 3 \text{ mA}$	1.65		0.08	0.24		0.24	
		$I_{OL} = 8 \text{ mA}$	2.3		0.20	0.3		0.3	
		I _{OL} = 12 mA	2.7		0.22	0.4		0.4	
		I _{OL} = 16 mA	3.0		0.28	0.4		0.4	
		I_{OL} = 24 mA	3.0		0.38	0.55		0.55	
		I _{OL} = 32 mA	4.5		0.42	0.55		0.55	
I _{IN}	Input Leakage Current	$V_{IN} = V_{CC}$ or GND	0 to 5.5			± 0.1		±1.0	μА
I _{CC}	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5			1		10	μΑ

AC ELECTRICAL CHARACTERISTICS t_{R} = t_{F} = 3.0 ns

			v _{cc}	T _A = 25°C		;	-40°C ≤	Γ _A ≤ 85°C	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
t _{PLH}	Propagation Delay	$R_L = 1 M\Omega$, $C_L = 15 pF$	1.65	2.0	5.5	12.0	2.0	12.7	ns
t _{PHL}	(Figure 3 and 4)	$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	1.8	2.0	4.6	10	2.0	10.5	
		$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	2.5 ± 0.2	0.8	3.0	7	0.8	7.5	
		$R_L = 1 M\Omega$, $C_L = 15 pF$	3.3 ± 0.3	0.5	2.6	4.7	0.5	5.0	
		$R_L = 500 \Omega, C_L = 50 pF$		1.5	3.0	5.2	1.5	5.5	
		$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	5.0 ± 0.5	0.5	2.2	4.1	0.5	4.4	
		$R_L = 500 \Omega, C_L = 50 pF$		0.8	2.4	4.5	0.8	4.8	

CAPACITIVE CHARACTERISTICS

Symbol	Parameter Condition		Typical	Unit
C _{IN}	Input Capacitance	$V_{CC} = 5.5 \text{ V}, V_I = 0 \text{ V or } V_{CC}$	>4	pF
C _{PD}	Power Dissipation Capacitance	10 MHz, V_{CC} = 3.3 V, V_{I} = 0 V or V_{CC}	25	pF
	(Note 5)	10 MHz, V_{CC} = 5.5 V, V_{I} = 0 V or V_{CC}	30	

^{5.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no-load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

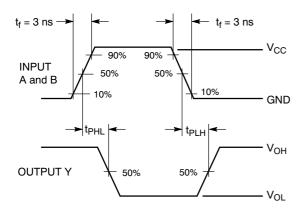
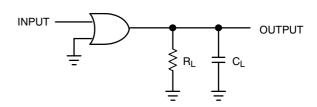


Figure 3. Switching Waveform



A 1 MHz square input wave is recommended for propagation delay tests.

Figure 4. Test Circuit

ORDERING INFORMATION

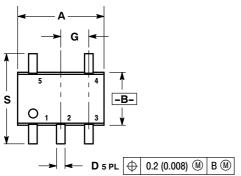
Device Order Number	Package Type	Tape and Reel Size [†]
NL17SZ32DFT2	SC70-5/SC-88A/SOT-353	3000 / Tape & Reel
NL17SZ32DFT2G	SC70-5/SC-88A/SOT-353 (Pb-Free)	3000 / Tape & Reel
NL17SZ32XV5T2	SOT-553*	4000 / Tape & Reel
NL17SZ32XV5T2G	SOT-553*	4000 / Tape & Reel

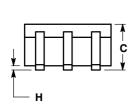
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

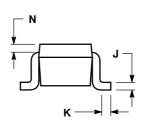
^{*}All Devices in Package SOT553 are Inherently Pb-Free.

PACKAGE DIMENSIONS

SC-88A, SOT-353, SC-70 CASE 419A-02 **ISSUE J**







NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

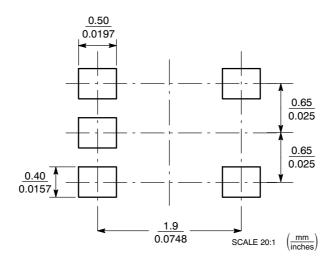
 2. CONTROLLING DIMENSION: INCH.

 3. 419A-01 OBSOLETE. NEW STANDARD 419A-02.

 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	INC	HES	MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
С	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026	BSC	0.65	BSC
Н		0.004	-	0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008	0.008 REF 0.20 REF		REF
S	0.079	0.087	2.00	2.20

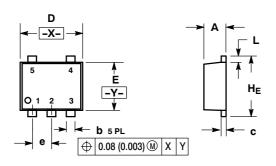
SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

SOT-553 XV5 SUFFIX 5-LEAD PACKAGE CASE 463B-01 ISSUE B



NOTES:

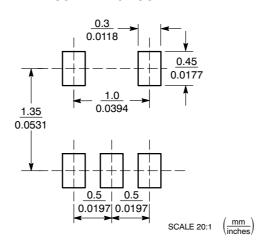
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS				INCHES		
DIM	MIN	NOM	MAX	MIN	MIN NOM		
Α	0.50	0.55	0.60	0.020	0.022	0.024	
b	0.17	0.22	0.27	0.007	0.009	0.011	
С	0.08	0.13	0.18	0.003	0.005	0.007	
D	1.50	1.60	1.70	0.059	0.063	0.067	
Е	1.10	1.20	1.30	0.043	0.047	0.051	
е		0.50 BSC		0.020 BSC			
Ĺ	0.10	0.20	0.30	0.004	0.008	0.012	
HE	1.50	1.60	1.70	0.059	0.063	0.067	

STYLE 1: PIN 1. BASE 1

- 2. EMITTER 1/2 3. BASE 2 4. COLLECTOR
- 4. COLLECTOR 2 5. COLLECTOR 1
- STYLE 2: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE

SOLDERING FOOTPRINT*



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